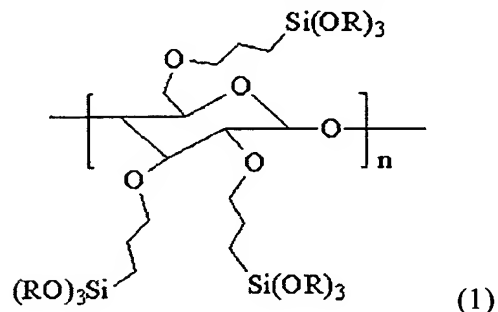


In the Claims:

Please rewrite the claims as follows:

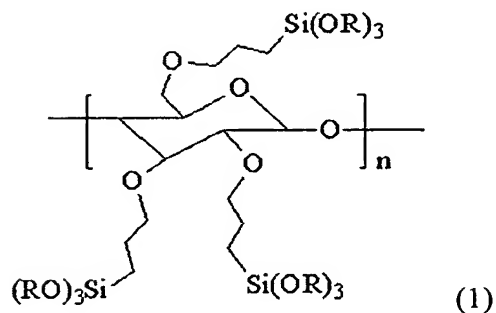
1. (Original) Reactive nanoparticular porogen based on cyclodextrin derivative of the following formula 1 to be used as a porogen,



wherein R represents the same or different C<sub>1-6</sub> alkyl group, respectively, wherein n is an integer of 6 to 12.

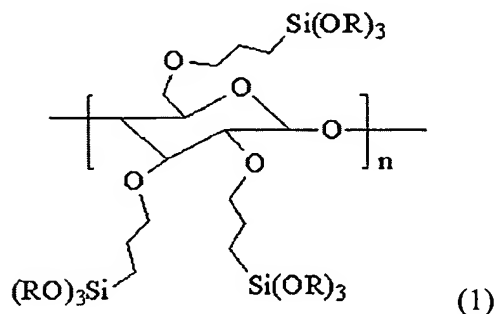
2. (Original) In claim 1, said derivative is selected from the group consisting of hexakis(2,3,6-tri-O-(3-trimethoxysilylpropyl)- $\alpha$ -cyclodextrin), hexakis(2,3,6-tri-O-(3-triethoxysilylpropyl)- $\alpha$ -cyclodextrin), heptakis(2,3,6-tri-O-(3-trimethoxysilylpropyl)- $\beta$ -cyclodextrin), heptakis(2,3,6-tri-O-(3-triethoxysilylpropyl)- $\beta$ -cyclodextrin), octakis(2,3,6-tri-O-(3-triethoxysilylpropyl)- $\gamma$ -cyclodextrin), and octakis(2,3,6-tri-O-(3-trimethoxysilylpropyl)- $\gamma$ -cyclodextrin).

3. (Original) A dielectric matrix manufactured by sol-gel reaction of a derivative of the following formula 1,



wherein R represents the same or different C<sub>1-6</sub> alkyl groups, respectively and wherein n is an integer of 6 to 12.

4. (Original) A low dielectric film manufactured by thin-filming of said dielectric matrix, which is manufactured by sol-gel reaction of the following formula 1,

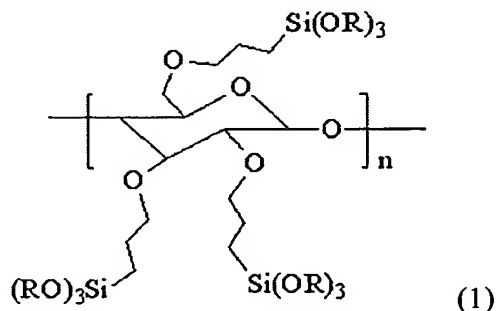


wherein R represents the same or different C<sub>1-6</sub> alkyl groups respectively and n is an integer of 6 to 12.

5. (Original) In claim 4, said dielectric matrix comprises a silicate precursor selected from polymethylsilsequioxane and polymethylsilsequioxane copolymer.

6. (Original) An ultralow dielectric composition comprising:

- a) an organic or inorganic silicate precursor, and
- b) a reactive nanoparticular porogen based on cyclodextrin derivative of the following formula 1,



wherein R represents the same or different C<sub>1-6</sub> alkyl group, respectively and n is an integer of 6 to 12.

7. (Original) In claim 6, said ultralow dielectric composition is obtained by combining (a) said organic or inorganic silicate precursor and (b) said nanoparticle of a cyclodextrin derivative of the above formula 1, which are dissolved to have the equal concentration within the range of from 10 to 40 wt.%, with a mixing ratio of 10-50: 10-50 vol.% between the two solutions.

8. (Original) In claim 6, said derivative of the above formula 1 is an ultralow dielectric composition selected from the group consisting of hexakis(2,3,6-tri-*O*-(3-trimethoxysilylpropyl)- $\alpha$ -cyclodextrin), hexakis(2,3,6-tri-*O*-(3-triethoxysilylpropyl)- $\alpha$ -cyclodextrin), heptakis(2,3,6-tri-*O*-(3-trimethoxysilylpropyl)- $\beta$ -cyclodextrin), heptakis(2,3,6-tri-*O*-(3-triethoxysilylpropyl)- $\beta$ -cyclodextrin), octakis(2,3,6-tri-*O*-(3-triethoxysilylpropyl)- $\gamma$ -cyclodextrin), and octakis(2,3,6-tri-*O*-(3-trimethoxysilylpropyl)- $\gamma$ -cyclodextrin).

9. (Original) In claim 6, said dielectric matrix comprises a silicate precursor selected from polymethylsilsequioxane and polymethylsilsequioxane copolymer.

10. (Currently Amended) An ultralow dielectric films manufactured by thin-filming of any one of the ultralow dielectric ~~compositions of claims 6—9~~ composition of claim 6, wherein the porosity is 21 to 51% and dielectric constant is 2.1 to 1.54 when the relative volume of the template solution with reference to the matrix solution is 40 to 49%.

11. (New) An ultralow dielectric films manufactured by thin-filming of any one of the ultralow dielectric composition of claim 7, wherein the porosity is 21 to 51% and dielectric constant is 2.1 to 1.54 when the relative volume of the template solution with reference to the matrix solution is 40 to 49%.

12. (New) An ultralow dielectric films manufactured by thin-filming of any one of the ultralow dielectric composition of claim 8, wherein the porosity is 21 to 51% and dielectric constant is 2.1

to 1.54 when the relative volume of the template solution with reference to the matrix solution is 40 to 49%.

13. (New) An ultralow dielectric films manufactured by thin-filming of any one of the ultralow dielectric composition of claim 9, wherein the porosity is 21 to 51% and dielectric constant is 2.1 to 1.54 when the relative volume of the template solution with reference to the matrix solution is 40 to 49%.